



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-03-24
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC58EC74E3E0C0X	B9YE*FC80ABQ	A	1054	2017-03-24
Amount	UoM	Unit type	ST ECOPACK Grade	
520.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14-14-1	100	gull wing	
Comment	TQFP 100 14x14x1.0 1.0 ExpadDown			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.68	Die / Leadframe	3233

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B9YE*FC80ABQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	59.818	mg	supplier	die	Silicon (Si)	7440-21-3		58.781	mg	982664	113040
				supplier	metallization	Aluminium (Al)	7429-90-5		0.123	mg	2056	237
				supplier	metallization	Copper (Cu)	7440-50-8		0.386	mg	6453	742
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.063	mg	1053	121
				supplier	metallization	Titanium (Ti)	7440-32-6		0.011	mg	185	21
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	33	4
				supplier	Passivation	Silicon Oxide	7631-86-9		0.452	mg	7556	869
Leadframe	Copper & its alloys	220.336	mg	supplier	alloy	Copper (Cu)	7440-50-8		218.283	mg	990682	419775
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.219	mg	995	421
				supplier	metallization	Nickel (Ni)	7440-02-0		1.681	mg	7629	3233
				supplier	metallization	Palladium (Pd)	7440-05-3		0.108	mg	490	208
				supplier	metallization	Gold (Au)	7440-57-5		0.045	mg	204	87
Die attach	Other Organic Materials	7.697	mg	supplier	glue	Silver (Ag)	7440-22-4		6.889	mg	895024	13248
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.577	mg	74964	1110
				supplier	glue	Bismaleimide resin	35325-39-4		0.231	mg	30012	444
				supplier	wire	Copper (Cu)	7440-50-8		0.808	mg	1000000	1554
Encapsulation	Other Organic Materials	231.342	mg	supplier	mold compound	Silica, vitreous	60676-86-0		199.879	mg	863998	384383
				supplier	mold compound	Epoxy Resin	25068-38-6		17.351	mg	75002	33367
				supplier	mold compound	Phenol Resin	29690-82-2		11.567	mg	50000	22244
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.157	mg	5000	2225
				supplier	mold compound	Quartz	14808-60-7		0.694	mg	3000	1335
				supplier	mold compound	Carbon black	1333-86-4		0.694	mg	3000	1335